
dsPIC30F2011/2012 Rev. A1 Silicon Errata

The dsPIC30F2011/2012 (Rev. A1) samples you have received were found to conform to the specifications and functionality described in the following documents:

- DS70157 – “dsPIC30F/33F Programmer’s Reference Manual”
- DS70139 – “dsPIC30F2011/2012/3012/3013 Data Sheet”
- DS70046 – “dsPIC30F Family Reference Manual”

The exceptions to the specifications in the documents listed above are described in this section. These exceptions are described for the specific devices that are listed below:

- dsPIC30F2011
- dsPIC30F2012

These devices may be identified by the following message that appears in the MPLAB[®] ICD 2 Output Window under MPLAB IDE, when a “Reset and Connect” operation is performed within MPLAB IDE:

```
Setting Vdd source to target
Target Device dsPIC30F2011 found,
revision = Rev 1001
...Reading ICD Product ID
Running ICD Self Test
...Passed
MPLAB ICD 2 Ready
```

The errata described in this section will be addressed in future revisions of dsPIC30F2011 and dsPIC30F2012 devices.

Silicon Errata Summary

The following list summarizes the errata described in this document:

1. **Malfunction of EMUC2 pin on dsPIC30F2011/2012**
On the dsPIC30F2011/2012, the EMUC2 pin is susceptible to negative voltage spikes and requires additional protection.
2. **MAC Class Instructions with ± 4 Address Modification**
Sequential MAC instructions, which prefetch data from Y data space using ± 4 address modification will cause an address error trap.
3. **Decimal Adjust Instruction**
The Decimal Adjust instruction, *DAW.b*, may improperly clear the Carry bit, C (SR<0>).
4. **Sequential Interrupts**
Sequential interrupts after modifying the CPU IPL, interrupt IPL, interrupt enable or interrupt flag may cause an address error trap.
5. **DISI Instruction**
The DISI instruction will not disable interrupts if a DISI instruction is executed in the same instruction cycle that the DISI counter decrements to zero.
6. **Output Compare Module**
The output compare module will produce a glitch on the output when an I/O pin is initially set high and the module is configured to drive the pin low at a specified time.
7. **Output Compare Module in PWM Mode**
Output compare will produce a glitch when loading 0% duty cycle in PWM mode. It will also miss the next compare after the glitch.
8. **INT0, ADC and Sleep Mode**
ADC event triggers from the INT0 pin will not wake-up the device from Sleep mode if the SMPI bits are non-zero.

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9. 4x and 8x PLL Mode

If 4x or 8x PLL mode is used, the input frequency range is 5 MHz-10 MHz instead of 4 MHz-10 MHz.

10. Sleep Mode

Execution of the Sleep instruction (`PWRSleep #0`) may cause incorrect program operation after the device wakes up from Sleep. The current consumption during Sleep may also increase beyond the specifications listed in the device data sheet.

11. I²C™ Module

When the I²C module is enabled, the dsPIC[®] DSC device generates a glitch on the SDA and SCL pins, causing a false communication start in a single-master configuration or a bus collision in a multi-master configuration.

12. I²C Module

The I²C module loses incoming data bytes when operating as an I²C slave.

13. I/O Port – Port Pin Multiplexed with IC1

The Port I/O pin multiplexed with the Input Capture 1 (IC1) function cannot be used as a digital input pin when the UART auto-baud feature is enabled.

14. I²C Module

After enabling the I²C module (`I2CEN = 1`), the S and P bit values are not correct.

15. I²C Module: 10-bit addressing mode

When the I²C module is configured for 10-bit addressing using the same address bits (A10 and A9) as other I²C device A10 and A9 bits may not work as expected.

16. Timer Module

Clock switching prevents the device from waking up from Sleep.

The following sections describe the errata and work around to these errata, where they may apply.

1. Module: Malfunction of EMUC2 pin on dsPIC30F2011/2012

On the dsPIC30F2011/2012 devices, the EMUC2 pin is susceptible to negative voltage spikes and requires additional protection.

Work around

The work around depends on the usage of the EMUC2 pin.

- If the EMUC2 pin is not used, terminate pin to ground through a 100 ohms resistor.
- If the EMUC2 pin is used for emulation, connect pin to the MPLAB ICD 2 EMUC signal through a 100 ohms resistor.
- If the EMUC2 pin is used for I/O, add low-pass RC filter on the pin, with C = 1 nF and R = 100 ohms with the capacitor junction on the pin.

2. Module: MAC Class Instructions with ± 4 Address Modification

Sequential MAC class instructions, which prefetch data from Y data space using ± 4 address modification will cause an address error trap. The trap occurs only when all the following conditions are true:

1. Two sequential MAC class instructions (or a MAC class instruction executed in a REPEAT or DO loop) that prefetch from Y data space.
2. Both instructions prefetch data from Y data space using the + = 4 or - = 4 address modification.
3. Neither of the instruction uses an accumulator write-back.

Work around

The problem described above can be avoided by using any of the following methods:

1. Inserting any other instruction between the two MAC class instructions.
2. Adding an accumulator write-back (a dummy write-back if needed) to either of the MAC class instructions.
3. Do not use the + = 4 or - = 4 address modification.
4. Do not prefetch data from Y data space.

3. Module: CPU – DAW.b Instruction

The Decimal Adjust instruction, DAW.b, may improperly clear the Carry bit, C (SR<0>), when executed.

Work arounds

Work around 1:

Check the state of the Carry bit prior to executing the DAW.b instruction. If the Carry bit is set, set the Carry bit again after executing the DAW.b instruction. Example 1 shows how the application should process the Carry bit during a BCD addition operation.

EXAMPLE 1: CHECK CARRY BIT BEFORE DAW.b

```
.include "p30f3013.inc"
.....
MOV.b #0x80, w0 ;First BCD number
MOV.b #0x80, w1 ;Second BCD number
ADD.b w0, w1, w2 ;Perform addition
BRA NC, L0 ;If C set go to L0
DAW.b w2 ;If not, do DAW and
BSET.b SR, #C ;set the carry bit
BRA L1 ;and exit
L0:DAW.b w2
L1:....
```

Work around 2: For C Language Source Code

For applications using C language, MPLAB C30 versions 1.20.04 or higher provide the following command-line switch that implements a work around for the erratum.

```
-merrata=psv
```

Refer to the "readme.txt" file in the MPLAB C30 v1.20.04 toolsuite for further details.

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4. Module: Interrupt Controller – Sequential Interrupts

When interrupt nesting is enabled (or NSTDIS (INTCON1<15>) bit is '0'), the following sequence of events will lead to an address error trap. The generic terms “Interrupt 1” and “Interrupt 2” are used to represent any two enabled dsPIC30F interrupts.

1. Interrupt 1 processing begins.
2. Interrupt 1 is negated by user software by one of the following methods:
 - CPU IPL is raised to Interrupt 1 IPL level or higher or
 - Interrupt 1 IPL is lowered to CPU IPL level or lower or
 - Interrupt 1 is disabled (Interrupt 1 IE bit set to '0') or
 - Interrupt 1 flag is cleared
3. Interrupt 2 with priority higher than Interrupt 1 occurs.

Work around

The user may disable interrupt nesting or execute a `DISI` instruction before modifying the CPU IPL or Interrupt 1 setting. A minimum `DISI` value of 2 is required if the `DISI` is executed immediately before the CPU IPL or Interrupt 1 is modified, as shown in Example 2. If the MPLAB C30 compiler is being used, one must inspect the Disassembly Listing in the MPLAB IDE file to determine the exact number of cycles to disable level 1-6 interrupts. One may use a large `DISI` value and then set the `DISICNT` register to zero, as shown in Example 3. A macro may also be used to perform this task, as shown in Example 4.

EXAMPLE 2: USING DISI

```
.include      "p30fxxxx.inc"
...
DISI#2 ; protect the disable of INT1
BCLRIECL, #INT1IE; disable interrupt 1
... ; next instruction protected by DISI
```

EXAMPLE 3: RAISING CPU INTERRUPT PRIORITY LEVEL

```
.include      "p30fxxxx.h"
...
__asm__ volatile ("DISI #0x1FFF"); // protect CPU IPL modification
SRbits.IPL = 0x5; // set CPU IPL to 5
DISICNT = 0x0; // remove DISI protection
```

EXAMPLE 4: USING MACRO

```
#define DISI_PROTECT(X) {\
    __asm__ volatile ("DISI #0x1FFF");\
    X; \
    DISICNT = 0; }

DISI_PROTECT(SRbits.IPL = 0x5); // safely modify the CPU IPL
```

5. Module: DISI Instruction

When a user executes a DISI #7, for example, this will disable interrupts for 7 + 1 cycles (7 + the DISI instruction itself). In this case, the DISI instruction uses a counter which counts down from 7 to 0. The counter is loaded with 7 at the end of the DISI instruction.

If the user code executes another DISI on the instruction cycle where the DISI counter has become zero, the new DISI count is loaded, but the DISI state machine does not properly re-engage and continue to disable interrupts. At this point, all interrupts are enabled. The next time the user code executes a DISI instruction, the feature will act normally and block interrupts.

In summary, it is only when DISI execution is coincident with the current DISI count = 0, that the issue occurs. Executing a DISI instruction before the DISI counter reaches zero will not produce this error. In this case, the DISI counter is loaded with the new value and interrupts remain disabled until the counter becomes zero.

Work around

When executing multiple DISI instructions within the source code, make sure that subsequent DISI instructions have at least one instruction cycle between the time that the DISI counter decrements to zero and the next DISI instruction. Alternatively, make sure that subsequent DISI instructions are called before the DISI counter decrements to zero.

6. Module: Output Compare Module

A glitch will be produced on an output compare pin under the following conditions:

- The user software initially drives the I/O pin high using the output compare module or a write to the associated PORT register.
- The output compare module is configured and enabled to drive the pin low at some later time (OCxCON = 0x0002 or OCxCON = 0x0003).

When these events occur, the output compare module will drive the pin low for one instruction cycle (T_{cy}) after the module is enabled.

Work around

None. However, the user may use a timer interrupt and write to the associated PORT register to control the pin manually.

7. Module: Output Compare in PWM Mode

If the desired duty cycle is '0' (OCxRS = 0), the module will generate a high level glitch of 1 T_{cy}. The second problem is that on the next cycle after the glitch, the OC pin does not go high, or in other words, it misses the next compare for any value written on OCxRS.

Work around

There are two possible solutions to this problem:

1. Load a value greater than '0' to the OCxRS register when operating in PWM mode. In this case, no 0% duty cycle is achievable.
2. If the application requires 0% duty cycles, the output compare module can be disabled for 0% duty cycles, and re-enabled for non-zero percent duty cycles.

8. Module: INT0, ADC and Sleep Mode

ADC event triggers from the INT0 pin will not wake-up the device from Sleep mode if the SMPI bits are non-zero. This means that if the ADC is configured to generate an interrupt after a certain number of INT0 triggered conversions, the ADC conversions will not be triggered and the device will remain in Sleep. The ADC will perform conversions and wake-up the device only if it is configured to generate an interrupt after each INT0 triggered conversion (SMPI<3:0> = 0000).

Work around

None. If ADC event trigger from the INT0 pin is required, initialize SMPI<3:0> to '0000' (interrupt on every conversion).

9. Module: 4x and 8x PLL Mode

If 4x or 8x PLL mode is used, the input frequency range is 5 MHz-10 MHz instead of 4 MHz-10 MHz.

Work around

None. If 4x or 8x PLL is used, make sure the input crystal or clock frequency is 5 MHz or greater.

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10. Module: Sleep Mode

Execution of the Sleep instruction (PWRSAV #0) may cause incorrect program operation after the device wakes up from Sleep. The current consumption during Sleep may also increase beyond the specifications listed in the device data sheet.

Work arounds

To avoid this issue, any of the following three work arounds can be implemented, depending on the application requirements.

Work around 1:

Ensure that the PWRSAV #0 instruction is located at the end of the last row of Program Flash Memory available on the target device and fill the remainder of the row with NOP instructions.

This can be accomplished by replacing all occurrences of the PWRSAV #0 instruction with a function call to a suitably aligned subroutine. The address() attribute provided by the MPLAB ASM30 assembler can be utilized to correctly align the instructions in the subroutine. For an application written in C, the function call would be GotoSleep(), while for an assembly language application, the function call would be CALL _GotoSleep.

The Address Error Trap Service Routine software can then replace the invalid return address saved on the stack with the address of the instruction immediately following the _GotoSleep or GotoSleep() function call. This ensures that the device continues executing the correct code sequence after waking up from Sleep mode.

Example 5 demonstrates the work around described above, as it would apply to a dsPIC30F2011 device.

EXAMPLE 5:

```
-----  
;-----  
.global __reset  
.global _main  
.global _GotoSleep  
.global __AddressError  
.global __INT1Interrupt  
;-----  
;-----  
.section *, code  
_main:  
    BSET    INTCON2, #INT1EP    ; Set up INT pins to detect falling edge  
    BCLR    IFS1, #INT1IF      ; Clear interrupt pin interrupt flag bits  
    BSET    IEC1, #INT1IE      ; Enable ISR processing for INT pins  
    CALL    _GotoSleep         ; Call function to enter SLEEP mode  
_continue:  
    BRA    _continue  
;-----  
; Address Error Trap  
__AddressError:  
    BCLR    INTCON1, #ADDRERR  
    ; Set program memory return address to _continue  
    POP.D   W0  
    MOV.B   #tblpage (_continue), W1  
    MOV     #tbloffset (_continue), W0  
    PUSH.D  W0  
    RETFIE  
;-----  
;-----  
__INT1Interrupt:  
    BCLR    IFS1, #INT1IF      ; Ensure flag is reset  
    RETFIE                      ; Return from Interrupt Service Routine  
;-----  
;-----  
.section *, code, address (0x1FC0)  
_GotoSleep:  
; fill remainder of the last row with NOP instructions  
    .rept 31  
        NOP  
    .endr  
; Place SLEEP instruction in the last word of program memory  
    PWRSAV #0  
-----
```

Work around 2:

Instead of executing a `PWRSVAV #0` instruction to put the device into Sleep mode, perform a clock switch to the 512 kHz Low-Power RC (LPRC) Oscillator with a 64:1 postscaler mode. This enables the device to operate at 0.002 MIPS, thereby significantly reducing the current consumption of the device. Similarly, instead of using an interrupt to wake-up the device from Sleep mode, perform another clock switch back to the original oscillator source to resume normal operation. Depending on the device, refer to **Section 7. "Oscillator"** (DS70054) or **Section 29. "Oscillator"** (DS70268) in the *"dsPIC30F Family Reference Manual"* (DS70046) for more details on performing a clock switch operation.

Note: The above work around is recommended for users for whom application hardware changes are not possible.

Work around 3:

Instead of executing a `PWRSVAV #0` instruction to put the device into Sleep mode, perform a clock switch to the 32 kHz Low-Power (LP) Oscillator with a 64:1 postscaler mode. This enables the device to operate at 0.000125 MIPS, thereby significantly reducing the current consumption of the device. Similarly, instead of using an interrupt to wake-up the device from Sleep mode, perform another clock switch back to the original oscillator source to resume normal operation. Depending on the device, refer to **Section 7. "Oscillator"** (DS70054) or **Section 29. "Oscillator"** (DS70268) in the *"dsPIC30F Family Reference Manual"* (DS70046) for more details on performing a clock switch operation.

Note: The above work around is recommended for users for whom application hardware changes are possible, and also for users whose application hardware already includes a 32 kHz LP Oscillator crystal.

11. Module: I²C Module

When the I²C module is enabled by setting the I2CEN bit in the I2CCON register, the dsPIC DSC device generates a glitch on the SDA and SCL pins. This glitch falsely indicates "Communication Start" to all devices on the I²C bus, and can cause a bus collision in a multi-master configuration.

Work arounds

To avoid this issue, any of the following two work arounds can be implemented, depending on the application requirements.

Work around 1:

In a single-master environment, add a delay between enabling the I²C module and the first data transmission. The delay should be equal to or greater than the time it takes to transmit two data bits.

In the multi-master configuration, in addition to the delay, all other I²C masters should be synchronized and wait for the I²C module to be initialized before initiating any kind of communication.

Work around 2:

In dsPIC DSC devices in which the I²C module is multiplexed with other modules that have precedence in the use of the pin, it is possible to avoid this glitch by enabling the higher priority module before enabling the I²C module.

Use the following procedure to implement this work around:

1. Enable the higher priority peripheral module that is multiplexed on the same pins as the I²C module.
2. Set up and enable the I²C module.
3. Disable the higher priority peripheral module that was enabled in step 1.

12. Module: I²C Module

When the I²C module is configured as a slave, either in single-master or multi-master mode, the I²C receiver buffer is filled whether a valid slave address is detected or not. Therefore, an I²C receiver overflow condition occurs and this condition is indicated by the I2COV flag in the I2CSTAT register.

This overflow condition inhibits the ability to set the I²C receive interrupt flag (SI2CF) when the last valid data byte is received. Therefore, the I²C slave Interrupt Service Routine (ISR) is not called and the I²C receiver buffer is not read prior receiving the next data byte.

Work arounds

To avoid this issue, either of the following two work arounds can be implemented, depending on the application requirements.

Work around 1:

For applications in which the I²C receiver interrupt is not required, the following procedure can be used to receive valid data bytes:

1. Wait until the RBF flag is set.
2. Poll the I²C receiver interrupt SI2CIF flag.
3. If SI2CF is not set in the corresponding Interrupt Flag Status (IFSx) register, a valid address or data byte has not been received for the current slave. Execute a dummy read of the I²C receiver buffer, I2CRCV; this will clear the RBF flag. Go back to step 1 until SI2CF is set and then continue to Step 4.
4. If the SI2CF is set in the corresponding Interrupt Flag Status (IFSx) register, valid data has been received. Check the D_A flag to verify that an address or a data byte has been received.
5. Read the I2CRCV buffer to recover valid data bytes. This will also clear the RBF flag.
6. Clear the I²C receiver interrupt flag SI2CF.
7. Go back to step 1 to continue receiving incoming data bytes.

Work around 2:

Use this work around for applications in which the I²C receiver interrupt is required. Assuming that the RBF and the I2COV flags in the I2CSTAT register are set due to previous data transfers in the I2C bus (i.e., between master and other slaves); the following procedure can be used to receive valid data bytes:

1. When a valid slave address byte is detected, SI2CF bit is set and the I²C slave interrupt service routine is called; however, the RBF and I2COV bits are already set due to data transfers between other I²C nodes.
2. Check the status of the D_A flag and the I2COV flag in the I2CSTAT register when executing the I²C slave service routine.
3. If the D_A flag is cleared and the I2COV flag are set, an invalid data byte was received but a valid address byte was received. The overflow condition occurred because the I²C receive buffer was overflowing with previous I²C data transfers between other I²C nodes. This condition only occurs after a valid slave address was detected.
4. Clear the I2COV flag and perform a dummy read of the I²C receiver buffer, I2CRCV, to clear the RBF bit and recover the valid address byte. This action will also avoid the loss of the next data byte due to an overflow condition.
5. Verify that the recovered address byte matches the current slave address byte. If they match, the next data to be received is a valid data byte.
6. If the D_A flag and the I2COV flag are both set, a valid data byte was received and a previous valid data byte was lost. It will be necessary to code for handling this overflow condition.

13. Module: I/O Port – Port Pin Multiplexed with IC1

If the user application enables the auto-baud feature in the UART module, the I/O pin multiplexed with the IC1 (Input Capture) pin cannot be used as a digital input.

Work around

None.

14. Module: I²C Module

After enabling the I²C module (I2CEN = 1), the S and P bits are set to '1' and '0' values, respectively. This means that there is some communication going on the bus and the I²C module must wait for the bus to become Idle. In this case, the I²C module will continue to wait for the bus to become Idle until it receives a STOP instruction.

Work arounds

Depending on your environment, the two following work arounds can be used.

Work around 1:

In a single-master environment, add a delay between enabling the I²C module and the first data transmission. The delay should be equal to or greater than the time it takes to transmit two data bits. In the multi-master configuration, in addition to the delay, all other I²C masters should be synchronized, and wait for the I²C module to be initialized before initiating any kind of communication.

Work around 2:

In dsPIC DSC devices in which the I²C module is multiplexed with other modules that have precedence in the use of the pin, it is possible to avoid this issue by enabling the higher priority module before enabling the I²C module.

Use the following procedure to implement this work around:

1. Enable the higher priority peripheral module that is multiplexed on the same pins as the I²C module.
2. Set up and enable the I²C module.
3. Disable the higher priority peripheral module that was enabled in step 1.

Note: Work around 2 works only for devices that share the SDA and SCL pins with another peripheral that has a higher precedence over the port latch, such as the UART. The priority is shown in the pin diagram located in the data sheet. For example, if the SDA and SCL pins are shared with the UART and SPI pins, and the UART has higher precedence on the port latch pin.

15. Module: I²C Module

If there are two I²C devices on the bus, one of them is acting as the Master receiver and the other as the Slave transmitter. Suppose that both devices are configured for 10-bit addressing mode, and have the same value in the A10 and A9 bits of their addresses. When the Slave select address is sent from the Master, both the Master and Slave acknowledges it. When the Master sends out the read operation, both the Master and the Slave enter into Read mode and both of them transmit the data. The resultant data will be the ANDing of the two transmissions.

Work around

Use different addresses including the higher two bits (A10 and A9) for different modules.

16. Module: Timer Module

When the timer is being operated in the asynchronous mode using the secondary oscillator (32.768 kHz) and the device is put into Sleep mode, a clock switch to any other oscillator mode before putting the device to Sleep prevents the timer from waking the device from Sleep.

Work around

Do not clock switch to any other oscillator mode if the timer is being used in the asynchronous mode using the secondary oscillator (32.768 kHz).

dsPIC30F2011/2012

APPENDIX A: REVISION HISTORY

Revision A (04/2006)

Original version of the document.

Revision B (9/2006)

Added issues 2, 5, 7, 9 and 10.

Revision C (09/2007)

Added issue 11 (Sleep Mode).

Revision D (12/2007)

Added issues 12 and 13 (I2C Module), and 14 (I/O Port – Port Pin Multiplexed with IC1).

Revision E (5/2008)

Added silicon issues 14 and 15 (I2C Module), and 16 (Timer Module). Removed silicon issue 8 (Using OSC2/RC15 pin for Digital I/O).

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